

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1-10. (canceled)

11. (original) A method of forming a flip chip package attached on a substrate provided with a plurality of contact pads, the method comprising the following steps:
providing an IC chip having a plurality of first solder bumps on a lower surface thereof;
providing a heat sink having a plurality of second solder bumps formed thereon;
placing the IC chip on the substrate such that the first solder bumps of the IC chip is aligned with the contact pads of the substrate;
placing the heat sink on the IC chip; and
reflowing the first and second solder bumps so as to securely attach the IC chip to the substrate and securely attach the heat sink to the IC chip at the same time.

12. (original) The method as claimed in claim 11, wherein the IC chip has a plurality of pads each made of under bump metallurgy (UBM) on an upper surface thereof, and the heat sink placing step includes aligning the second solder bumps of the heat sink with the pads of the IC chip.

13. (original) The method as claimed in claim 11 further comprising the steps of: forming an underfill between the IC chip and the heat sink and between the IC chip and the substrate respectively; and curing the underfill.

14. (original) The method as claimed in claim 11, wherein the heat sink is made of metal.

15. (original) The method as claimed in claim 11, wherein the heat sink is a dummy chip without wiring formed therein.